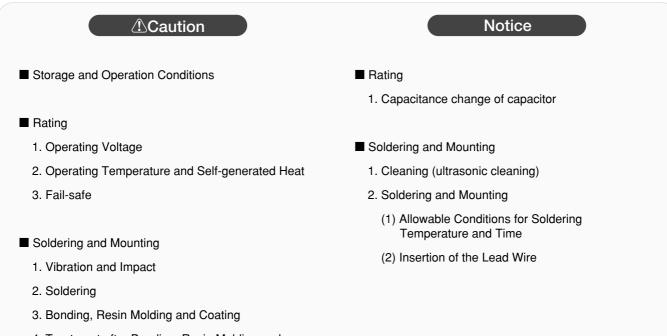
## **Caution/Notice**



4. Treatment after Bonding, Resin Molding and Coating

## 

### Storage and Operation Conditions

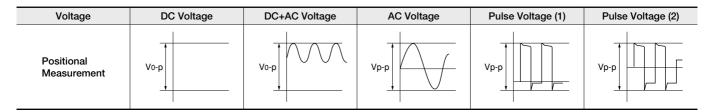
The insulating coating of capacitors does not form a perfect seal; therefore, do not use or store capacitors in a corrosive atmosphere, especially where chloride gas, sulfide gas, acid, alkali, salt or the like are present. Also avoid exposure to moisture. Before cleaning, bonding or molding this product, verify that these processes do not affect product quality by testing the performance of a cleaned, bonded or molded product in the intended equipment. Store the capacitors where the temperature and relative humidity do not exceed 5 to 40 degrees centigrade and 20 to 70%. Use capacitors within 6 months after delivery.

### Rating

### 1. Operating Voltage

When DC-rated capacitors are to be used in AC or ripple current circuits, be sure to maintain the Vp-p value of the applied voltage or the V0-p which contains DC bias within the rated voltage range.

When the voltage is applied to the circuit, starting or stopping may generate irregular voltage for a transit period because of resonance or switching. Be sure to use a capacitor with a rated voltage range that includes these irregular voltages. When DC-rated capacitors are to be used in input circuits from commercial power source (AC filter), be sure to use Safety Recognized Capacitors because various regulations on withstand voltage or impulse withstand established for all equipment should be taken into consideration.



#### 2. Operating Temperature and Self-generated Heat

Keep the surface temperature of a capacitor below the upper limit of its rated operating temperature range. Be sure to take into account the heat generated by the capacitor itself. When the capacitor is used in a high-frequency current, pulse current or similar current, it may have self-generated heat due to dielectric loss. In the case of "High Dielectric Constant Type Capacitors," applied voltage load should be such that self-generated heat is within 20 °C under the condition where the capacitor is subjected at an atmosphere temperature of 25 °C. Please contact us if self-generated heat occurs with "Temperature Compensating Type Capacitors".

### 3. Fail-Safe

Be sure to provide an appropriate fail-safe function on your product to prevent a second damage that may be caused by the abnormal function or the failure of our product. When measuring, use a thermocouple of small thermal capacity -K of Ø0.1mm under conditions where the capacitor is not affected by radiant heat from other components or wind from surroundings. Excessive heat may lead to deterioration of the capacitor's characteristics and reliability. Never attempt to perform measurement with the cooling fan running. Otherwise, accurate measurement cannot be ensured.



## 

### Continued from the preceding page.

### Soldering and Mounting

### 1. Vibration and Impact

Do not expose a capacitor or its leads to excessive shock or vibration during use.

### 2. Soldering

When soldering this product to a PCB/PWB, do not exceed the solder heat resistance specification of the capacitor. Subjecting this product to excessive heating could melt the internal junction solder and may result in thermal shocks that can crack the ceramic element.

### 3. Bonding, Resin Molding and Coating

In case of bonding, molding or coating this product, verify that these processes do not affect the quality of the capacitor by testing the performance of the bonded, molded or coated product in the intended equipment.

In case the amount of application, dryness/ hardening conditions of adhesives and molding resins containing organic solvents (ethyl acetate, methyl ethyl ketone, toluene, etc.) are unsuitable, the outer coating resin of a capacitor may be damaged by the organic solvents and may result, worst case, in a short circuit.

The variation in thickness of adhesive or molding resin or coating may cause an outer coating resin cracking and/or ceramic element cracking of a capacitor in a temperature cycling.

4. Treatment after Bonding, Resin Molding and Coating When the outer coating is hot (over 100 degrees centigrade) after soldering, it becomes soft and fragile, so please be careful not to give it mechanical stress.

FAILURE TO FOLLOW THE ABOVE CAUTIONS MAY RESULT, WORST CASE, IN A SHORT CIRCUIT AND CAUSE FUMING OR PARTIAL DISPERSION WHEN THE PRODUCT IS USED.



### Notice

### Rating

1. Capacitance change of capacitor

In case of F/X7R/X7S/X7T/X8L/Y5V/Z5U char. Capacitors have an aging characteristic, whereby the capacitor continually decreases its capacitance slightly if the capacitor is left on for a long time. Moreover, capacitance might change greatly depending on the surrounding temperature or an applied voltage.

### Soldering and Mounting

1. Cleaning (ultrasonic cleaning)

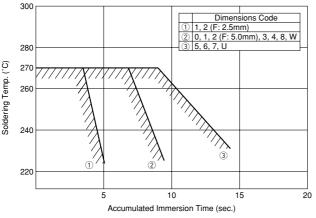
To perform ultrasonic cleaning, observe the following conditions.

Rinse bath capacity: Output of 20 watts per liter or less. Rinsing time: 5 min. maximum.

Do not vibrate the PCB/PWB directly.

Excessive ultrasonic cleaning may lead to fatigue destruction of the lead wires.

### 2. Soldering and Mounting



Perform soldering within tolerance range (shaded portion).

- (2) Insertion of the Lead Wire
- When soldering, insert the lead wire into the PCB without mechanically stressing the lead wire.
- Insert the lead wire into the PCB with a distance appropriate to the lead space.



	Rated Voltage	DC	25V			DC50V				DC100V		DC250V	DC630V	DC1kV
	Temp. Char.	X7S	X7R	C0G	X7S	X7R	F	Y5V	C0G	X7S	X7R		X7R, U2J	
0		224K	(104K	A	-	224K		(103Z)	A	-	(224K)	-	-	-
1			-	\/	-		-	-	\/	_		U 102J	_	-
2		(M475 K2C)	-	_	(M 475 K5C)	(M <sup>105</sup> K5C)	-	-	_	_	(M 105 K1C)	(103 J4U (U2J) (U2J) (MK4C (X7R)	(U2J) (U2J) (X7R)	(U2J) (U2J) (MAC) (X7R)
3, 4, W		(M226 K2C	_	_	_	(M335 K5C)	_	_	_	(M225 K1C)	_	(M 473 J4U (U2J) (M 224 K4C (X7R)	(M 103 J7U (U2J) (M 104 K7C (X7R)	(M472 JAU (U2J) (M333 KAC (X7R)
5, U		_	_	_	_	_	_	_	_	_	_	- (M 474 K4C (X7R)	(M 333 J7U (U2J) (U2J) (U2J) (U2J) (U2J) (U2J) (U2J)	(U2J) (U2J) (U2J) (M 104 KAC (X7R)
Temperatur Characteristi						/X7R char narking ex		V char.: F	, U2J cha	r.: U)				
Nominal Capaci	itance	Under 10	0pF: Actu	ial value	100pF a	nd over: N	larked wit	n 3 figures	5					
Capacitance Tole	erance	Marked with code A part is omitted (Please refer to the marking example.)												
Rated Voltag	ge	Lower ho	Marked with code (DC25V: 2, DC50V: 5, DC100V: 1, DC250V: 4, DC500V: 9, DC630V: 7, DC1kV: A) Lower horizontal line for F char. A part is omitted (Please refer to the marking example.)											
Manufacture Identificatio		Marked v A part is	-	Please refe	er to the n	narking ex	ample.)							

# RDE Series (Only for Commercial) Specifications and Test Methods

	_		Specifi	cations			_	
No.	Ite	m	Temperature Compensating Type	High Dielectric Constant Type	- Test Method			
1	Operating Temperature Range		-55 to +125°C	Char. X7R, X7S: -55 to +125°C Char. F: -25 to +85°C Char. Y5V: -30 to +85°C		-		
2	Appearance		No defects or abnormalities	Visual inspection	n			
3	Dimension an	d Marking	See previous pages		Visual inspection	n, Vernier Calipe	r	
					voltages of Tabl for 1 to 5 sec. (C	e are applied bet Charge/Discharge	maged when test ween the terminals e current $\leq$ 50mA)	
		Between Terminals	No defects or abnormalities		Temperature     [       Compensating     [       Type     [       High Dielectric     [       Constant Type     [	DC250V         2           DC630V         1           DC1kV         1           DC25V, DC50V         2           DC100V, DC250V         2           DC500V, DC630V         1	Test Voltage         300% of the rated voltage         200% of the rated voltage         50% of the rated voltage         30% of the rated voltage         200% of the rated voltage	
4	4 Dielectric Strength	Body Insulation	No defects or abnormalities		diameter so that short-circuited, i approximately 2 as shown in the sec. between ca	etal balls of 1mn each terminal, s kept mm from the ball figure, for 1 to 5 pacitor terminals (Charge/Dischar	Approx. 2mm	
				Rated Volta				
				DC100V DC250V		f the rated voltage		
				DC100V, DC23 DC500V, DC63 DC1kV	30V <sup>200% 01</sup>	f the rated voltage		
5	Insulation Resistance       Between Terminals       Rated Voltage: DC25V, DC50V, DC100V 10,000MΩ min. or 500MΩ • μF min. whichever is smaller         Rated Voltage: DC250V, DC500V, DC630V, DC1kV 10,000MΩ min. or 100MΩ • μF min. whichever is smaller			<sup>-</sup> min. whichever is smaller )V, DC630V, DC1kV	The insulation re DC voltage not e (DC500±50V in DC630V, DC1kV and within 2 mir	esistance should exceeding the rat case of rated vlo /) at normal temp	be measured with a ted voltage tage: DC500V, berature and humidity	
6	Capacitance	·	Within the specified tolerance		The capacitance, Q/D.F. should be measured at 25°C at the frequency and voltage shown in the table.			
						0		
				Temperature Co Capacitan Item	ce C≦1000pF			
					Frequency	1±0.1MHz	1±0.1kHz	
7	Q/Dissipation	Factor (D.F.)	30pF min.: Q≧1,000 30pF max.: Q≧400+20C	Char. X7R: 0.025 max. Char. F, Y5V: 0.05 max.	Voltage AC0.5 to 5V AC			
			C: Nominal capacitance (pF)	Char. X7S: 0.125 max.	High Dielectric (	Constant Type		
					Capacitan Item	ce C≦10μF	C>10µF	
					Frequency	1±0.1kHz	120±24Hz	
					Voltage	AC1±0.2V		
			1	1		(r.m.s.)	(r.m.s.)	

Continued on the following page.  $\square$ 

# RDE Series (Only for Commercial) Specifications and Test Methods

Continued from the preceding page.

				cations				
No.	Iter	n	Temperature Compensating Type	High Dielectric Constant Type	Test Method			
		Capacitance Change	Within the specified tolerance (Table A on last column)	Within the specified tolerance (Table B on last column)	The capacitance change should be measured a min. at each specified temperature stage. (1) Temperature Compensating Type The temperature coefficient is determined using capacitance measured in step 3 as a reference cycling the temperature sequentially from step through 5 (-55 to +125°C) the capacitance shou within the specified tolerance for the temperature			
8	Capacitance Temperature	Temperature Coefficient	Within the specified tolerance (Table A on last column)		coefficient and cap A. The capacitance differences betwee	acitance change as shown in Table e drift is calculated by dividing the n the maximum and minimum n step 1, 3 and 5 by the cap. value in Temperature (°C)		
0	Characteristics				<u> </u>	25±2		
					2	-55±3		
					3	25±2		
					4	125±3		
		Capacitance Drift	Within ±0.2% or ±0.05pF, whichever is larger		25°C (Char. F: 20°C ranges as shown ir specified ranges. • Pretreatment (for Perform a heat trea then let sit at room	25±2 Constant Type acitance change compared with the C) value over the temperature in Table B should be within the high dielectric constant type) atment at 150+0/-10°C for 1 hr., and temperature for 24±2 hrs. the capacitor body, apply the force		
9	Terminal Strength	Tensile Strength	Termination not to be broken or	loosened	gradually to each le	ead in the radial direction of the hing 10N and then keep the force		
		Bending Strength	Termination not to be broken or	loosened	and then bent 90° a direction. Each wire	uld be subjected to a force of 2.5N at the point of egress in one e is then returned to the original 0° in the opposite direction at the er 2 to 3 sec.		
		Appearance	No defects or abnormalities		The capacitor is so	Idered securely to a supporting		
	Vibuction	Capacitance	Within the specified tolerance		· ·	o 55Hz vibration of 1.5mm peak-		
10	Vibration Resistance	Q/D.F.	30pF min.: Q≧1,000 30pF max.: Q≧400+20C C: Nominal capacitance (pF)	Char. X7R: 0.025 max. Char. F, Y5V: 0.05 max. Char. X7S: 0.125 max.	mutually perpendic	applied for 6 hrs. total, 2 hrs. in each ular direction. Allow 1 min. to cycle 10Hz to 55Hz and the converse.		
11	1 Solderability of Leads		Lead wire should be soldered wi direction over 3/4 of the circumfe	8	The terminal of a capacitor is dipped into a 25% ethat (JIS-K-8101) solution of rosin (JIS-K-5902) and then into molten solder for 2±0.5 sec. In both cases t depth of dipping is up to about 1.5mm to 2mm from t terminal body. Temp. of solder: 245±5°C Lead Free Solder (Sn-3.0Ag-0.50 235±5°C H60A or H63A Eutectic Solder			
		Appearance	No defects or abnormalities		The load wire is in	margad in the meltad addrest From		
	Resistance to	Capacitance Change	Within ±2.5% or ±0.25pF (whichever is larger)	Char. X7R, X7S: Within ±10% Char. F, Y5V: Within ±20%	to 2mm from the m sec.	mersed in the melted solder 1.5mm ain body at 350±10°C for 3.5±0.5		
12	Soldering Heat	Dielectric Strength (Between Terminals)	No defects	·	<ul> <li>The specified items are measured after 24±2 hrs.</li> <li>Pretreatment (for high dielectric constant type)</li> <li>Perform a heat treatment at 150+0/-10°C for 1 hr., and then let sit at room temperature for 24±2 hrs.</li> </ul>			

Continued on the following page.  $\overline{\nearrow}$ 

# RDE Series (Only for Commercial) Specifications and Test Methods

Continued from the preceding page.

lo.	Iter	m	Specifi	cations	Test Method				
0.	Iter		Temperature Compensating Type	High Dielectric Constant Type					
		Appearance	No defects or abnormalities						
		Capacitance Change	Within ±5% or ±0.5pF (whichever is larger)	Char. X7R, X7S: Within ±12.5% Char. F, Y5V: Within ±30%	The capacitor should be subjected to 5 temperature cycles.				
		Q/D.F.	30pF min.: Q≧350 10pF to 30pF: Q≧275+5C/2 10pF max.: Q≧200+10C	Remove and set for 24±2 hrs. at room temperature, then measure.       Step     Temperature (°C)					
2	Temperature		C: Nominal capacitance (pF)	Char. X7S: 0.2 max.	1	Min. Operating Tem		30±3	
13 C <sub>3</sub>	Cycle	Insulation Resistance	Rated Voltage: DC25V, DC50V, 1,000MΩ, 50MΩ • μF min. (wh Rated Voltage: DC250V, DC500 1,000MΩ, 10MΩ • μF min. (wh	ichever is smaller) IV, DC630V, DC1kV	2 3 4	Room Temp. Max. Operating Tem Room Temp.		3 max. 30±3 3 max.	
		Dielectric Strength (Between Terminals)	No defects or abnormalities		<ul> <li>Pretreatment (for high dielectric constant type)</li> <li>Perform a heat treatment at 150+0/-10°C for 1 hr., a</li> <li>then let sit at room temperature for 24±2 hrs.</li> </ul>			for 1 hr., ar	
		Appearance	No defects or abnormalities						
		Capacitance Change	Within ±5% or ±0.5pF (whichever is larger)	Char. X7R, X7S: Within ±15% Char. F, Y5V: Within ±30%	Set the capa	acitor at 40±2°C and r	elative l	numidity of	
4	Humidity (Steady State)	Q/D.F.	30pF min.: Q≥350 10pF to 30pF: Q≥275+5C/2 10pF max.: Q≥200+10C C: Nominal capacitance (pF)	Char. X7R: 0.05 max. Char. F, Y5V: 0.075 max. Char. X7S: 0.2 max.	90 to 95% for 500± <sup>2</sup> 6 hrs. Remove and set for 24±2 hrs. at room temper then measure. • Pretreatment (for high dielectric constant typ Perform a heat treatment at 150+0/-10°C for 1 then let sit at room temperature for 24±2 hrs.			ric constant type)	
		Insulation Resistance	Rated Voltage: DC25V, DC50V, 1,000MΩ, 50MΩ • μF min. (wh Rated Voltage: DC250V, DC500 1,000MΩ, 10MΩ • μF min. (wh	ichever is smaller) IV, DC630V, DC1kV					
		Appearance	No defects or abnormalities						
		Capacitance Change	Within ±7.5% or ±0.75pF (whichever is larger)	Char. X7R, X7S: Within ±15% Char. F, Y5V: Within ±30%	Apply the rated voltage for $500^{+24}_{-0}$ hrs. at $40\pm2^{\circ}$ C and in 90 to 95% humidity.				
5	Humidity Load	Q/D.F.	30pF min.: Q≧200 30pF max.: Q≧100+10C/3 C: Nominal capacitance (pF)	Char. X7R: 0.05 max. Char. F, Y5V: 0.075 max. Char. X7S: 0.2 max.	<ul> <li>Remove and set for 24±2 hrs. at room temperative then measure.</li> <li>(Charge/Discharge current ≤50mA)</li> <li>Pretreatment (for high dielectric constant type Perform a heat treatment at 150+0/-10°C for 1 then let sit at room temperature for 24±2 hrs.</li> </ul>				
		Insulation Resistance	Rated Voltage: DC25V, DC50V, 500MΩ or 25MΩ • μF min. (wf Rated Voltage: DC250V, DC500 1,000MΩ or 10MΩ • μF min. (v	nichever is smaller) IV, DC630V, DC1kV				for 1 hr., ar	
		Appearance	No defects or abnormalities		Apply voltage in Table for $1000^{+48}_{-0}$ hrs. at the				
		Capacitance Within ±3% or ±0.3pF		Char. X7R, X7S: Within ±15% (Rated Voltage: DC630V or less)	maximum operating temperature±3°C. Remove and set for 24±2 hrs. at room temperature, then measure. (Charge/Discharge current ≤50mA)				
	High	Change	(whichever is larger)	Within ±20% (Rated Voltage: DC1kV) Char. F, Y5V: Within ±30%	Temperature Compensating	DC250V		<b>/oltage</b> rated voltage	
6	Temperature Load	Q/D.F.	30pF min.: Q≧350 10pF to 30pF: Q≧275+5C/2 10pF max.: Q≧200+10C C: Nominal capacitance (pF)	Char. X7R: 0.05 max. Char. F, Y5V: 0.075 max. Char. X7S: 0.2 max.	Type High Dielectric Constant Type	c DC25V, DC50V, DC100V, DC250V 15 DC500V, DC630V 12	0% of the 0% of the	rated voltage rated voltage	
		Insulation Resistance	Rated Voltage: DC25V, DC50V, 1,000MΩ, 50MΩ • μF min. (wh Rated Voltage: DC250V, DC500 1,000MΩ, 10MΩ • μF min. (wh	Appy test vo	DC1kV 11 ent (for high dielectric litage for 1 hr., at test d set for 24±2 hrs. at r	constan tempera	ature.		
		Appearance	No defects or abnormalities			or should be fully imm			
7 Solvent Resistance		Marking	Legible	reagent at 20 to 25°C for 30±5 sec. and then remove gently. Marking on the surface of the capacitor shoul immediately be visually examined. Reagent: • Isopropyl alcohol					

### Table A

Char.	Nominal Values	С	apacitar	nce Char	nge from	25°C (%	%)
	Nominal Values (ppm/°C) *1	–55°C		–30°C		–10°C	
	(ppm/°C) "T	Max.	Min.	Max.	Min.	Max.	Min.
C0G	0±30	0.58	-0.24	0.40	-0.17	0.25	-0.11
U2J	-750±120	8.78	5.04	6.04	3.47	3.84	2.21

\*1: Nominal values denote the temperature coefficient within a range of 25 to 125°C

Table B							
Char.	Temp. Range	Reference Temp.	Cap. Change Rate				
X7R	–55 to +125°C		Within ±15%				
X7S	-55 10 +125 C	25°C	Within ±22%				
Y5V	-30 to + 85°C		Within _음을%				
F	-25 to + 85°C	20°C	Within ±38%				

### Packaging

Two types of packaging for monolithic ceramic capacitors are available.

### 1. Bulk Packaging

### Minimum Quantity

Dimensions Code	Dimensions (L×W)	Minimum Quantity (pcs./Bag)*
0	3.6×3.5mm or 4.0×3.5mm or 5.0×3.5mm (Depends on Part Number)	
1	4.0×3.5mm or 4.5×3.5mm or 5.0×3.5mm (Depends on Part Number)	
2	5.0×3.5mm or 5.5×4.0mm or 5.7×4.5mm (Depends on Part Number)	
3	5.0×4.5mm or 5.5×5.0mm or 6.0×5.5mm (Depends on Part Number)	500
4	7.5×5.5mm	500
5	7.5×7.5mm or 7.5×8.0mm (Depends on Part Number)	
6	10.0×10.0mm	
8	7.5×5.5mm	
7	12.5×12.5mm	100
U	7.7×12.5mm or 7.7×13.0mm (Depends on Part Number)	200
W	5.5×7.5mm or 6.0×8.0mm (Depends on Part Number)	500

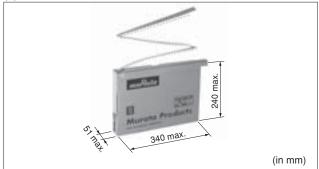
Please order with an integral multiple of the minimum quantity above.

\* Minimum Quantity may change depends on part number.

Please check our website 'Product details'.

### 2. Tape Carrier Packaging

(1) Dimensions of Ammo Pack



#### (2) Minimum Quantity

Dimensions Code	Dimensions (L×W)	Minimum Quantity (pcs./Ammo Pack)*
0	3.6×3.5mm or 4.0×3.5mm or 5.0×3.5mm (Depends on Part Number)	
1	4.0×3.5mm or 4.5×3.5mm or 5.0×3.5mm (Depends on Part Number)	
2	5.0×3.5mm or 5.5×4.0mm or 5.7×4.5mm (Depends on Part Number)	2000
3	5.0×4.5mm or 5.5×5.0mm or 6.0×5.5mm (Depends on Part Number)	
4	7.5×5.5mm	
5	7.5×7.5mm or 7.5×8.0mm (Depends on Part Number)	2000
6	10.0×10.0mm	4500
8	7.5×5.5mm	- 1500
U	7.7×12.5mm or 7.7×13.0mm (Depends on Part Number)	1000
W	5.5×7.5mm or 6.0×8.0mm (Depends on Part Number)	1500

Please order with an integral multiple of the minimum quantity above.

\* Minimum Quantity may change depends on part number.

Please check our website 'Product details'.

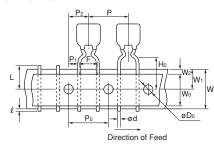
"Minimum Quantity" means the numbers of units of each delivery or order. The quantity should be an integral multiple of the "minimum quantity". (Please note that the actual delivery quantity in a package may change sometimes.)



### Solution Continued from the preceding page.

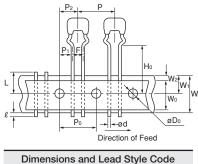
### Taping Dimensions

## Inside Crimp Taping

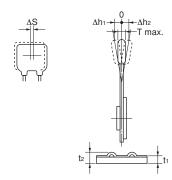


Dimensions and Lead Style Code
0M1
1M1
2M1
2M2
3M1
3M2
4M1
4M2
8M1
8M2
WM1

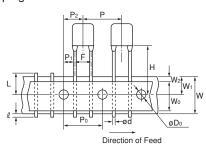
## Outside Crimp Taping



Dimensions and Lead Otyle Odde
0S1
1S1
2S1
2S2
3S1
3S2



### Straight Taping



Dimensions and Lead Style Code
1DB
2DB
3DB
5E1
5E2
6E1
6E2
UE1

lkene	Code	Dimensions (mm)		
Item		Dimensions (mm)		
Pitch of Component	P	12.7±1.0		
Pitch of Sprocket Hole	Po	12.7±0.2		
Lead Spacing	F	2.5 <sup>+0.4</sup> <sub>-0.2</sub> (DB) (S1) (S2)		
		5.0 <sup>+0.6</sup> -0.2		
Length from Hole Center to Component Center	P2	6.35±1.3		
	D.	3.85±0.7		
Length from Hole Center to Lead	P1	5.1±0.7 (DB) (S1) (S2)		
Leau	254±1.	5 Total length of components pitch $ imes$ 20		
Body Dimension	[	Depends on Part Number		
Deviation Along Tape, Left or Right Defect	ΔS	±2.0		
Carrier Tape Width	W	18.0±0.5		
Position of Sprocket Hole	W1	9.0 <sup>+0</sup> _0.5		
Lead Distance between	Ho	16.0±0.5 (M1) (S1)		
Reference and Bottom Plane		20.0±0.5 (M2) (S2)		
For Straight Lead Type	Н	20±0.5 (E2),17.5±0.5 (E1),16±0.5 (DB)		
Diameter of Sprocket Hole	Do	4.0±0.1		
Lead Diameter	d	0.5±0.05		
Total Tape Thickness	t1	0.6±0.3		
Total Thickness of Tape and Lead Wire	t2	1.5 max.		
Body Thickness	Т	Depends on Part Number		
		2.0 max. Dimensions Code: W, U		
Deviation Across Tape	$\Delta h_1$ $\Delta h_2$	1.5 max. RHD Series		
		1.0 max. except as above		
Portion to Cut in Case of Defect	L	11.0+0		
Protrusion Length	l	0.5 max.		
Hold Down Tape Width	Wo	9.5 min.		
Hold Down Tape Position	W2	1.5±1.5		
Coating Extension	[	Depends on Dimensions		